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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Box Patent Application Commissioner of Patents and Trademarks Washington, D.C. 20231

Re:	Inventor(s):

Liang-Yuh Chen, Wei-Yung Hsu, Alain Duboust, Ratson Morad, Daniel A.

Carl, Sasson Somekh, and Dan Maydan

Title:

Planarization of Substrates Using Electrochemical Mechanical Polishing

Transmitted herewith is the patent application identified above, including:

- Specification, claims and abstract, totaling 49 pages. <u>X</u>
- <u>X</u> Drawings totaling 19 pages, X Formal Informal.
- X Unexecuted Declaration and Power of Attorney.
- Information Disclosure Statement w/ Form 1449 and References.
- Assignment of the invention to Applied Materials, Inc.
- **Assignment Recordation Cover Sheet**

FEE CALCULATION

	NUMBER OF CLAIMS FILED	LESS NUMBER PAID BY BASIC FEE	NUMBER OF EXTRA CLAIMS (Not less than zero)	LARGE ENTITY FEE
Basic Fee				\$740.00
Total Claims	39	- 20 = 19	X \$18 =	\$342.00
Independent Claims	4	- 3 = 1	X \$84 =	\$84.00
First Presentation of Multiple Dependent Claims +250			-0-	
Total Filing Fee Calculation			\$1,166.00	
The Commissioner is hereby authorized to charge to Deposit Account No.				

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 The Commissioner is hereby authorized to charge any additional fees which may be
required, or credit any overpayment to Deposit Account No A duplicate copy
of this transmittal is enclosed

<u>X</u> Please address all future correspondence to:

PATENT COUNSEL APPLIED MATÉRIALS, INC. Legal Affairs Department P.O.BOX 450A Santa Clara, CA. 95052

Respectfully submitted,

B. Todd Patterson

Registration No. 37,906

I hereby certify that this correspondence is being deposited with the United States Postal Service as express mail in an envelope addressed to: of Commissioner Patents and Trademarks, Washington, D.C. 20231.

EV041916468US Express Mail Receipt No. 01/03/02 Date of Deposit Signature